ISCAS 2026

2026 IEEE International Symposium on Circuits and Systems









CALL FOR CROSS-SOCIETY SPECIAL PAPERS

The Organizing Committee of ISCAS 2026 invites proposals for Cross-Society Special Sessions to be held during the conference in Shanghai, China, 24–27 May 2026.

These sessions are designed to complement the regular technical program by showcasing emerging research areas, transformative ideas, and innovative applications that span across traditional disciplinary boundaries.

Proposals should focus on timely, high-impact topics that are likely to stimulate cross-disciplinary collaboration and attract broad interest. All papers submitted to Cross-Society Special Sessions will undergo the same rigorous peer-review process as regular submissions to ensure the highest quality standards.

Proposal Guidelines:

- □ Each Cross-Society Special Session must be jointly organized by members from at least two different IEEE societies (with supporting letter from the conference organizer).
- Organizers are expected to have successfully organized a similar special session at the respective flagship conferences of at least two IEEE societies. This helps in building momentum and visibility for the topic, and in attracting high-quality submissions from a broad spectrum of researchers.

Proposal should include the following information (3 pages max.)

- 1. Title and abstract: A title and a concise abstract
- **2.** *Rationale:* Explain why the topic is emerging and timely, describe its relevance to the ISCAS community and alignment with the innovation themes (if applicable).
- 3. **Proposed speakers:** Provide a list of all talks, speakers, and co-authors (in each associated paper). Technical sessions are normally expected to have 5 papers.
- 4. Short biographies: Provide a short bio-sketch of the session proposers.
- **5. Email Support:** An supporting email will be required at the submission of proposal from other societies. Please contact Yongfu Li to obtain email support from ISCAS'26 if you need it to get support from us while communicating with other conference organizers.

Special Session Co-Chairs

Yongfu Li

Shanghai Jiao Tong Univ.

Xiaojun Guo

Shanghai Jiao Tong Univ.

Shouyi Yin

Tsinghua University

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Qing Luo
Inst. of Microelectronics, CAS



2026.ieee-iscas.org

Proposals will be evaluated based on the relevance and timeliness of the topic, technical quality and track record of organizers and speakers, coherence and added value to the ISCAS 2026 program. The Involvement of industry speakers is encouraged and will be viewed positively.

Honorary Chair:

Junfa Mao

Shenzhen University

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Yong Lian York University Ming Liu Fudan University Shao-Jun Wei Tsinghua University

Gianluca Setti King Abdullah University of Science and Tech.

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